

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Sadayuki Kobayashi</td><td>09/26/2008</td></tr><tr><td>Daisuke Sato</td><td>09/26/2008</td></tr><tr><td>Masaru Akita</td><td>09/26/2008</td></tr><tr><td>Hiroshi Jinnai</td><td>10/06/2008</td></tr><tr><td>Takashi Inoue</td><td>10/14/2008</td></tr></tbody></table>	Name	Execution Date	Sadayuki Kobayashi	09/26/2008	Daisuke Sato	09/26/2008	Masaru Akita	09/26/2008	Hiroshi Jinnai	10/06/2008	Takashi Inoue	10/14/2008	
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<table border="1"><tr><td>Name:</td><td>Toray Industries, Inc.</td></tr><tr><td>Street Address:</td><td>1-1 Nihonbashi-Muromachi 2-chome</td></tr><tr><td>Internal Address:</td><td>Chuo-ku</td></tr><tr><td>City:</td><td>Tokyo</td></tr><tr><td>State/Country:</td><td>JAPAN</td></tr><tr><td>Postal Code:</td><td>103-8666</td></tr></table>	Name:	Toray Industries, Inc.	Street Address:	1-1 Nihonbashi-Muromachi 2-chome	Internal Address:	Chuo-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	103-8666	
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PROPERTY NUMBERS Total: 1													
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CORRESPONDENCE DATA													
Fax Number: (215)656-2498 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone: 215-656-3381													
Email: ip.phil@dlapiper.com													
Correspondent Name: T.Daniel Christenbury													
Address Line 1: One Liberty Place													
Address Line 2: 1650 Market Street, Suite 4900													
Address Line 4: PHILADELPHIA, PENNSYLVANIA 19103													
ATTORNEY DOCKET NUMBER:	TIP-08-1314												

CH \$40.00 12293697

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PATENT
REEL: 021743 FRAME: 0751

NAME OF SUBMITTER:

Carol Coney

Total Attachments: 1

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ASSIGNMENT

WHEREAS, we, Sadayuki Kobayashi, Daisuke Sato, Masaru Akita, Hiroshi Jinnai, and Takashi Inoue, citizens of Japan, respectively, residing at c/o Nagoya Plant, Toray Industries, Inc., 9-1, Oe-cho, Minato-ku, Nagoya-shi, Aichi, 455-8502 Japan; c/o Nagoya Plant, Toray Industries, Inc., 9-1, Oe-cho, Minato-ku, Nagoya-shi, Aichi, 455-8502 Japan; c/o Nagoya Plant, Toray Industries, Inc., 9-1, Oe-cho, Minato-ku, Nagoya-shi, Aichi, 455-8502 Japan; Katsura-Dai2-Godo 6-207, 65-3, Kawashima Gotan-nagamachi, Nishikyo-ku, Kyoto-shi, Kyoto, 615-8104 Japan; and 1406-3, Tooyama-cho, Yonezawa-shi, Yamagata, 992-0066 Japan, respectively, (hereinafter referred to as "the undersigned"), having made an invention entitled THERMOPLASTIC RESIN COMPOSITION, PRODUCTION METHOD THEREOF, AND MOLDED ARTICLE, identified in International Application No. PCT/JP2007/055825, and US Application No. 12/293,697, (DLA Piper is authorized to insert the Serial No. when known),

WHEREAS, Toray Industries, Inc., with offices located at 1-1, Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo, 103-8666 Japan (hereinafter referred to as "the assignee"), is desirous of acquiring the entire right, title and interest in said invention, said US application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, do hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said US application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention in the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on the date(s) set forth below.

Sep. 26, 2008
Date

Sadayuki Kobayashi
Sadayuki Kobayashi

Sep. 26, 2008
Date

Daisuke Sato
Daisuke Sato

Sep. 26, 2008
Date

Masaru Akita
Masaru Akita

Oct. 6, 2008
Date

Hiroshi Jinnai
Hiroshi Jinnai

Oct. 14, 2008
Date

Takashi Inoue
Takashi Inoue

PATENT